

# 22<sup>nd</sup> Annual Components for Military & Space Electronics Conference & Exhibition

May 7-10<sup>th</sup>, 2018

Four Points by Sheraton (LAX)  
Los Angeles, California

## Call for Presentations

The premier event focused on the design, reliability, and application of electronic components for use in avionics, aerospace, military & commercial space systems.

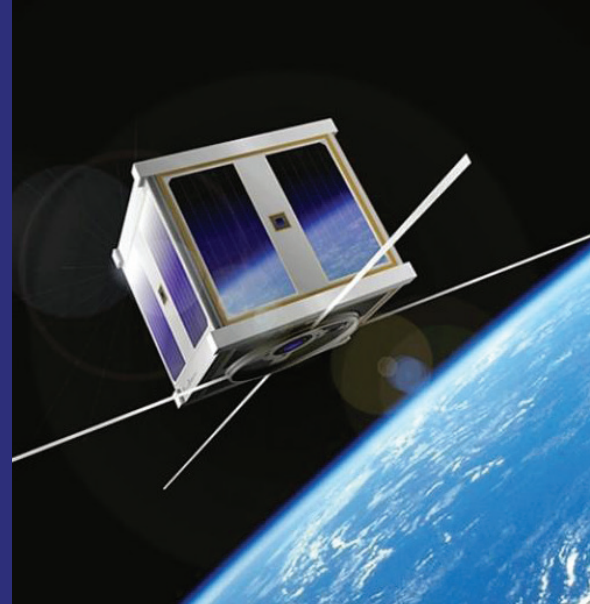
You are requested to submit an outline for a presentation at CMSE on topics such as:

- Advanced Packaging for Military and Space
- SIP 2.5- 3D and Wafer Level Packaging WLP
- Energy Efficient Electronics
- 3D Printed Passives
- GaN and SiC for RF Microwave and High Temp Use
- COTS Insertion and Obsolescence Challenges
- IC Copper Wire Bonding & Reliability
- Polymer Tantalum Capacitor Issues
- BME/PME MLCCs for Hi-Rel Applications
- Magnetics, Transformers and Inductors
- Secure Electronics (anti-tampering) Trusted
- Challenges of Non-Hermetic Packages
- Hermeticity and TM 1014/1018 New Spec Limits
- Supplier Base Sourcing Issues

## Deadline for Submission: October 27, 2017

Presentations are 20 minutes with 5 minutes of Q & A. The CMSE committee does not require a formal paper submission. You decide how much of the presentation material to provide the attendee. The idea is to promote sharing of basic scientific and technical information about common problems faced by both the component manufacturer and the system OEM.

Please email your presentation outline to [CMSE@tjgreenllc.com](mailto:CMSE@tjgreenllc.com).



**Tom Green**

*Technical Co-Chair*

**Leon Hamiter**

*Technical Co-Chair*

**Tom Terlizzi**

*Exhibits Chair*



Organized by: TJ Green Associates LLC